UHMWPE POROUS MATERIAL

SUNMAP LC-TW1

Features

- As SUNMAP is a porous sintered material having an open-cell structure; it offers the excellent air and moisture permeability.
- As SUNMAP is made of porous UHMWPE having high wear resistance and low friction coefficient the slip properties of SUNMAP is enhanced.
- SUNMAP offers good chemical resistance against typical acids and alkalis.
- Antistatic type

Structure

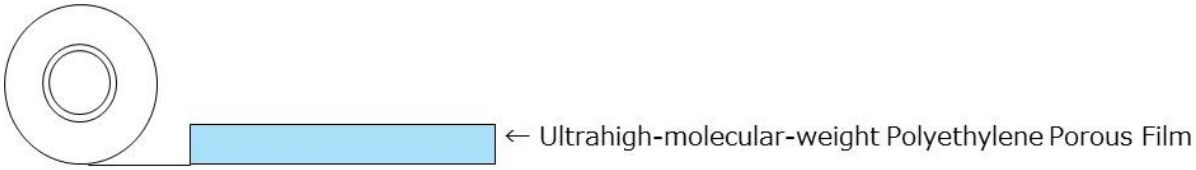

Fig.1 Structure

Applications

- Suction conveyance of ceramic green sheets
- Pick and place of electronic components
- Fixing of LCD panels during cutting
- Fixing of glass/ceramic substrates during cutting
- Fixing of FPC boards during screen printing
- Fixing of semiconductor wafers during dicing
- Fixing of lenses during polishing
- Enhancement of sliders of electronic equipment
- Protection of cables in cable chains and prevention of abrasion of sliders
- Prevention of creaking noise and abrasion inside cars

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Properties

Table.1 General properties

Property	Unit	Characteristic value			Test method
Thickness	mm	0.2	0.3	0.5	–
Air permeability	$cm^3/cm^2/sec$	6.0	3.8	1.0	JIS L 1096
Pore size	μm	17			–
Porosity	%	30			–
Tensile strength	MPa	12			JIS C 2107
Elongation	%	90			JIS C 2107
Hardness	Shore D	48			ASTM D2240
Surface Roughness（Ra）	μm	2.0			JIS B 0601
Coefficient of kinetic friction	–	0.1			JIS K 7125
Surface resistance	Ω/□	1×10^{10}			JIS K 7194

Standard Products Size

Table.2 Roll type

Thickness（mm）	Width（mm）	Length（m）
0.2	600～1000	10
0.3		
0.5		

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